



## FDN5632N\_F085

### N-Channel Logic Level PowerTrench® MOSFET

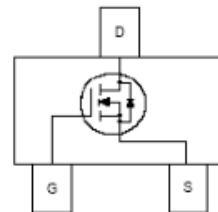
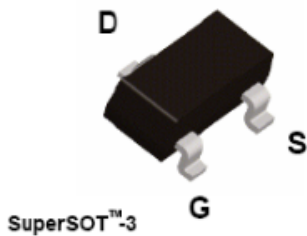
60V, 1.6A, 98mΩ

#### Features

- $R_{DS(on)} = 98m\Omega$  at  $V_{GS} = 4.5V$ ,  $I_D = 1.6A$
- $R_{DS(on)} = 82m\Omega$  at  $V_{GS} = 10V$ ,  $I_D = 1.7A$
- Typ  $Q_{g(TOT)} = 9.2nC$  at  $V_{GS} = 10V$
- Low Miller Charge
- Qualified to AEC Q101
- RoHS Compliant

#### Applications

- DC/DC converter
- Motor Drives



**MOSFET Maximum Ratings**  $T_A = 25^\circ\text{C}$  unless otherwise noted

| Symbol         | Parameter  | Ratings     | Units            |
|----------------|--|-------------|------------------|
| $V_{DSS}$      | Drain to Source Voltage                            | 60          | V                |
| $V_{GS}$       | Gate to Source Voltage                             | $\pm 20$    | V                |
| $I_D$          | Drain Current Continuous ( $V_{GS} = 10\text{V}$ ) | 1.7         | A                |
|                | Pulsed   | 10          |                  |
| $P_D$          | Power Dissipation                                  | 1.1         | W                |
| $T_J, T_{STG}$ | Operating and Storage Temperature                  | -55 to +150 | $^\circ\text{C}$ |

**Thermal Characteristics**

|                 |   |     |                    |
|-----------------|---|-----|--------------------|
| $R_{\theta JC}$ | Thermal Resistance Junction to Case   | 75  | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient TO-252, 1in <sup>2</sup> copper pad area | 111 | $^\circ\text{C/W}$ |

**Package Marking and Ordering Information**

| Device Marking | Device        | Package | Reel Size | Tape Width | Quantity   |
|----------------|---------------|---------|-----------|------------|------------|
| 5632           | FDN5632N_F085 | SSOT3   | 7"        | 8mm        | 3000 units |

**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--------|-----------|-----------------|-----|-----|-----|-------|
|--------|-----------|-----------------|-----|-----|-----|-------|

**Off Characteristics**

|            |                                   |  |    |   |           |               |
|------------|-----------------------------------|--|----|---|-----------|---------------|
| $B_{VDSS}$ | Drain to Source Breakdown Voltage | $I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$     | 60 | - | -         | V             |
| $I_{DSS}$  | Zero Gate Voltage Drain Current   | $V_{DS} = 48\text{V},$<br>$V_{GS} = 0\text{V}$ | -  | - | 1         | $\mu\text{A}$ |
|            |                                   | $T_A = 125^\circ\text{C}$                      | -  | - | 250       |               |
| $I_{GSS}$  | Gate to Source Leakage Current    | $V_{GS} = \pm 20\text{V}$                      | -  | - | $\pm 100$ | nA            |

**On Characteristics**

|              |                                  |  |   |     |     |            |
|--------------|----------------------------------|--|---|-----|-----|------------|
| $V_{GS(th)}$ | Gate to Source Threshold Voltage | $V_{GS} = V_{DS}, I_D = 250\mu\text{A}$                                | 1 | 2.0 | 3   | V          |
| $r_{DS(on)}$ | Drain to Source On Resistance    | $I_D = 1.7\text{A}, V_{GS} = 10\text{V}$                               | - | 57  | 82  | m $\Omega$ |
|              |                                  | $I_D = 1.6\text{A}, V_{GS} = 6\text{V}$                                | - | 62  | 88  |            |
|              |                                  | $I_D = 1.6\text{A}, V_{GS} = 4.5\text{V}$                              | - | 70  | 98  |            |
|              |                                  | $I_D = 1.7\text{A}, V_{GS} = 10\text{V},$<br>$T_A = 150^\circ\text{C}$ | - | 107 | 135 |            |

**Dynamic Characteristics**

|              |                               |   |  |     |     |          |    |
|--------------|-------------------------------|---|--|-----|-----|----------|----|
| $C_{iss}$    | Input Capacitance             | $V_{DS} = 15\text{V}, V_{GS} = 0\text{V},$<br>$f = 1\text{MHz}$ | -  | 475 | -   | pF       |    |
| $C_{oss}$    | Output Capacitance            |   | -  | 60  | -   | pF       |    |
| $C_{riss}$   | Reverse Transfer Capacitance  |   | -  | 30  | -   | pF       |    |
| $R_G$        | Gate Resistance               | $f = 1\text{MHz}$   | -  | 1.4 | -   | $\Omega$ |    |
| $Q_{g(TOT)}$ | Total Gate Charge at 10V      | $V_{GS} = 0$ to 10V   | $V_{DD} = 20\text{V}$<br>$I_D = 1.7\text{A}$ | -   | 9.2 | 12       | nC |
| $Q_{gs}$     | Gate to Source Gate Charge    |   |  | -   | 1.5 | -        | nC |
| $Q_{gd}$     | Gate to Drain "Miller" Charge |   |  | -   | 1.4 | -        | nC |

**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--------|-----------|-----------------|-----|-----|-----|-------|
|--------|-----------|-----------------|-----|-----|-----|-------|

**Switching Characteristics**

| Symbol       | Parameter           | Test Conditions  | Min | Typ | Max  | Units |
|--------------|---------------------|--|-----|-----|------|-------|
| $t_{on}$     | Turn-On Time        | $V_{DD} = 30\text{V}$ , $I_D = 1.0\text{A}$<br>$V_{GS} = 10\text{V}$ , $R_{GEN} = 6\Omega$ | -   | -   | 30   | ns    |
| $t_{d(on)}$  | Turn-On Delay Time  |  | -   | 15  | -    | ns    |
| $t_r$        | Rise Time           |  | -   | 1.7 | -    | ns    |
| $t_{d(off)}$ | Turn-Off Delay Time |  | -   | 5.2 | -    | ns    |
| $t_f$        | Fall Time           |  | -   | 1.3 | -    | ns    |
| $t_{off}$    | Turn-Off Time       |  | -   | -   | 12.9 | ns    |

**Drain-Source Diode Characteristics**

| Symbol   | Parameter                     | Test Conditions   | Min | Typ  | Max  | Units |
|----------|-------------------------------|---|-----|------|------|-------|
| $V_{SD}$ | Source to Drain Diode Voltage | $I_{SD} = 1.7\text{A}$  | -   | 0.8  | 1.25 | V     |
|          |                               | $I_{SD} = 0.85\text{A}$   | -   | 0.8  | 1.0  |       |
| $t_{rr}$ | Reverse Recovery Time         | $I_{SD} = 1.7\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$ | -   | 16.0 | 21   | ns    |
| $Q_{rr}$ | Reverse Recovery Charge       |   | -   | 7.9  | 10.3 | nC    |

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: <http://www.aecouncil.com/>

All Fairchild Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

### Typical Characteristics

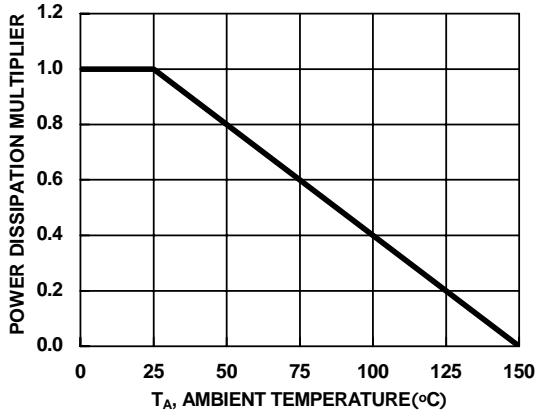


Figure 1. Normalized Power Dissipation vs Ambient Temperature

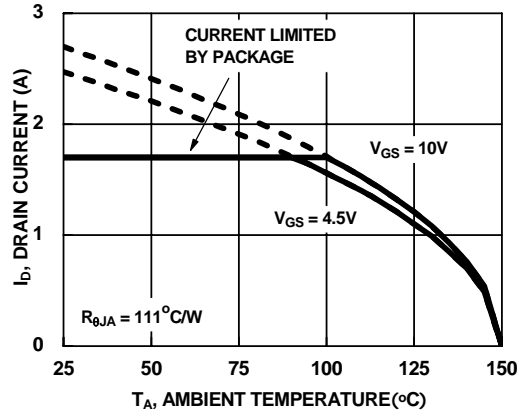


Figure 2. Maximum Continuous Drain Current vs Ambient Temperature

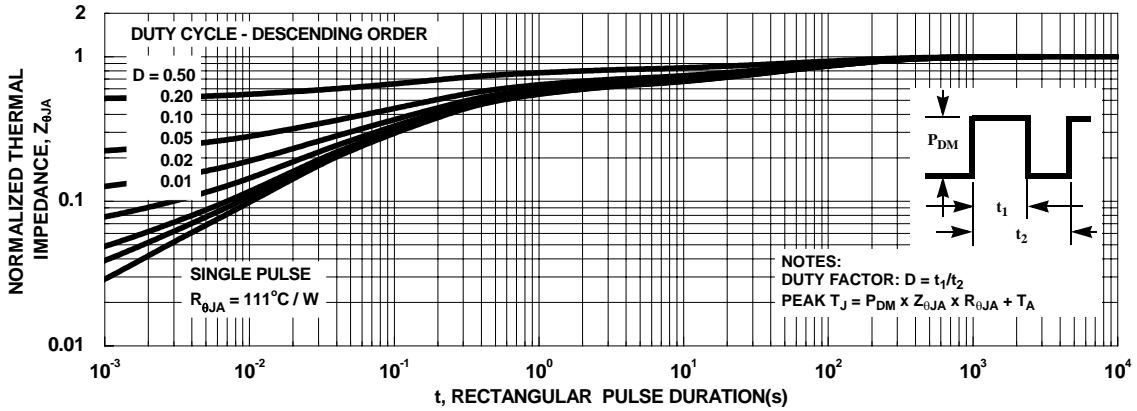


Figure 3. Normalized Maximum Transient Thermal Impedance

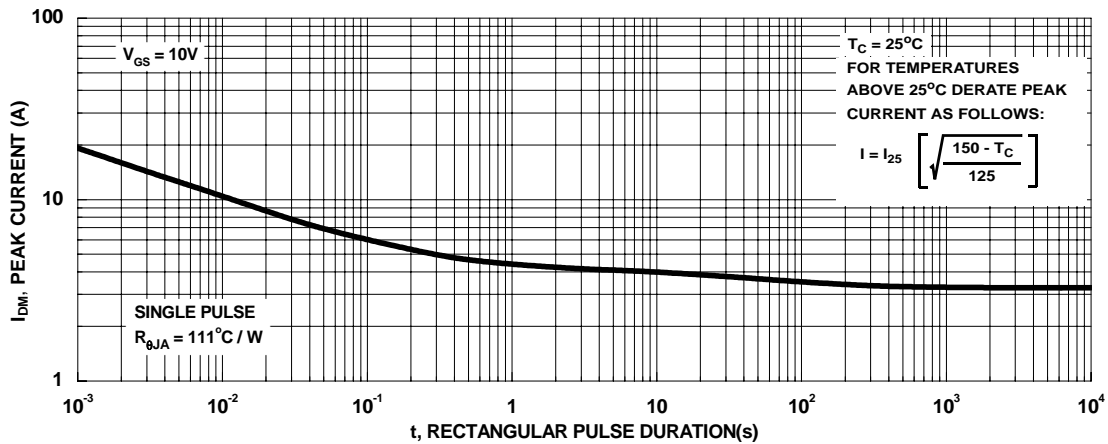


Figure 4. Peak Current Capability

## Typical Characteristics

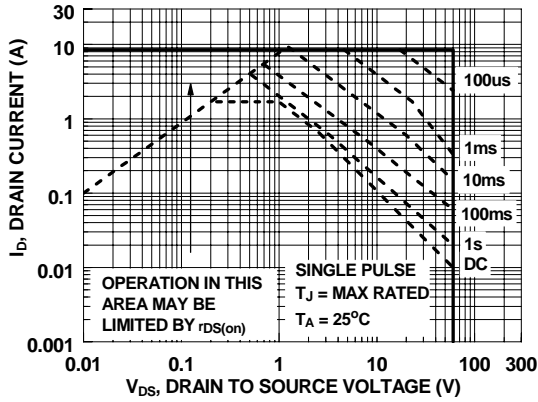


Figure 5. Forward Bias Safe Operating Area

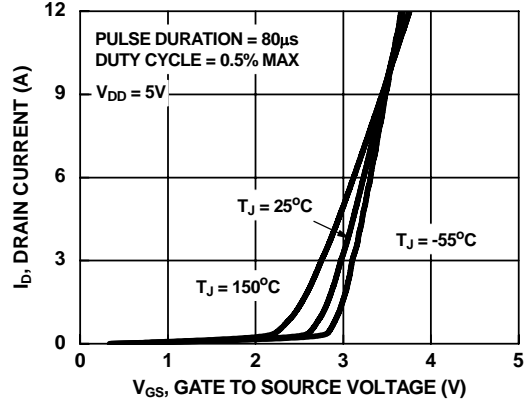


Figure 6. Transfer Characteristics

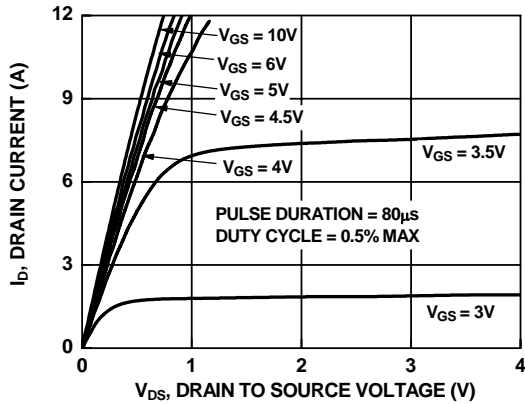


Figure 7. Saturation Characteristics

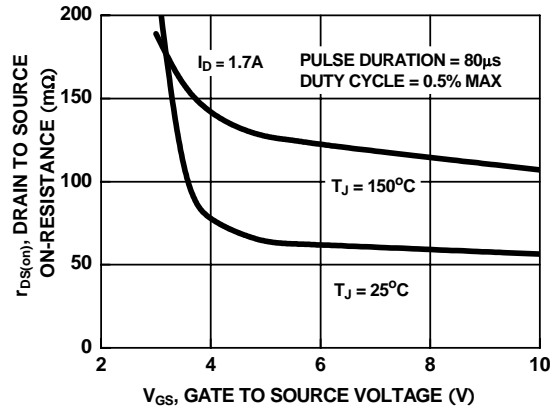


Figure 8. Drain to Source On-Resistance Variation vs Gate to Source Voltage

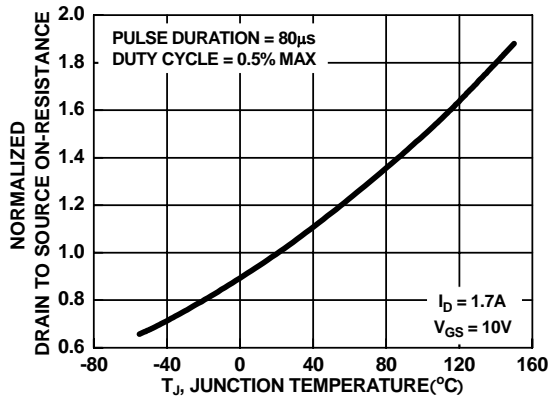


Figure 9. Normalized Drain to Source On-Resistance vs Junction Temperature

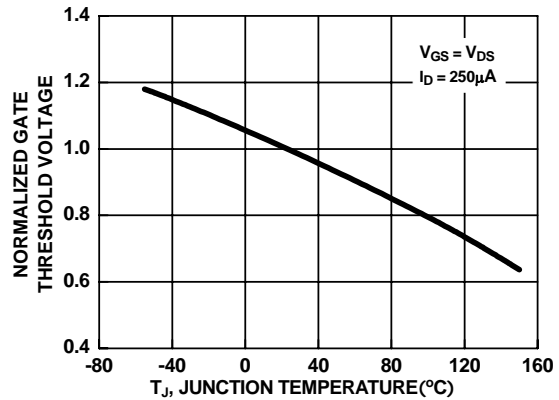


Figure 10. Normalized Gate Threshold Voltage vs Junction Temperature

## Typical Characteristics

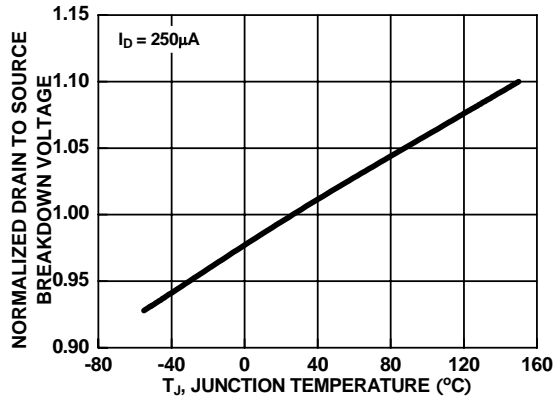


Figure 11. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

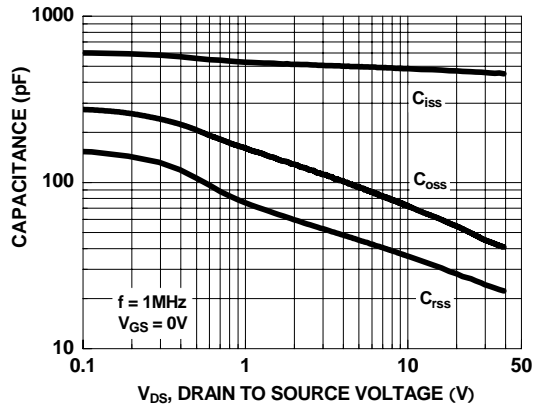


Figure 12. Capacitance vs Drain to Source Voltage

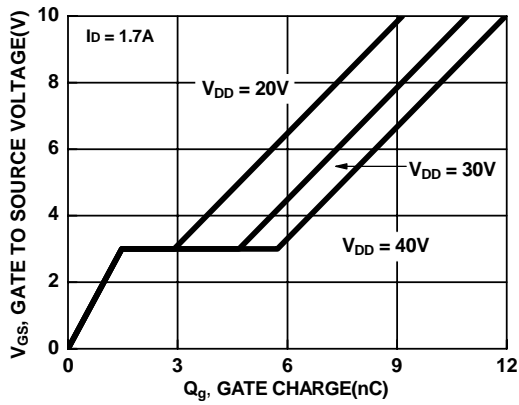








Figure 13. Gate Charge vs Gate to Source Voltage



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